



SAC™ (semi-aqueous chemistry) Remover

Aqueous-organic formulations that quickly and completely remove all types of post-etch residue under ambient conditions.

The Semi-Aqueous Chemistry (SAC™) series of products comprise the industry's most effective and elegant solution to the cleaning of etch residue at or below critical dimensions of 0.25µm. Used at ambient temperature for short process times, SAC™ products eliminate W plug failures and facilitate advanced interconnect by complete cleaning of both subtractive etch and damascene structures. Compatible with a wide variety of low-k dielectrics as well as Cu, Al, W and all commonly used barrier materials, these products are water rinseable and provide wide process latitude and long bath life. Their excellent surface activity reduces surface metal ion contamination by several orders of magnitude, offering a dramatic improvement over alternate cleaning strategies including other wet/dry or ashing technologies.

Currently three products comprise the SAC™ family: EKC630™, EKC640™, and EKC650™. Each of the formulations is tailored, ideally to service a particular niche within advanced interconnect cleaning. However, the diversity of different process integration schemes that exist mandates that these classifications serve as a guide only.

EKC600™ SERIES

EKC630™

This chemistry is designed for use in wet bench applications for cleaning metal, via, and damascene processes. Compatible with all standard materials employed in advanced interconnect. Room temperature operation for 2-5 minutes is typical, followed by a water rinse.

EKC640™

Specifically conceived for single wafer tool applications, EKC640™ is a fast-acting cleaning chemistry best suited for situations where a premium is placed on high throughput. However, the quick, effective performance of the product does not preclude its delivery to the wafer surface by other methods.

EKC645™ "NEW"

EKC645™ is the newest addition to EKC's EKC600™ Series of products. This chemistry has been specifically designed using an industry accepted alternative solvent system. EKC645™ is effective at removing post-etch residue during both via and metal processing. EKC645™ has a process window which supports effective processing of sub 0.18 micron features as well as larger geometry's.

EKC650™ & EKC652™ "NEW"

The EKC650™ chemistry has been fine-tuned for applications involving highly sensitive low-k dielectrics. This product is flexible for use in either a spray tool or wet bench, to be followed by a DI rinse.

EKC offers applications engineering support for all products. This includes product development and sustaining engineering solutions. On-site consulting, process evaluation and/or additional wafer testing are available through EKC's applications engineering or R & D as needed.

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